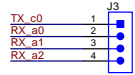
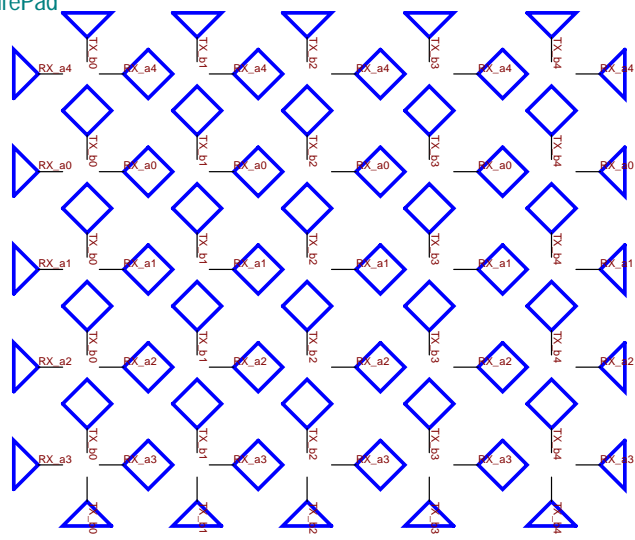


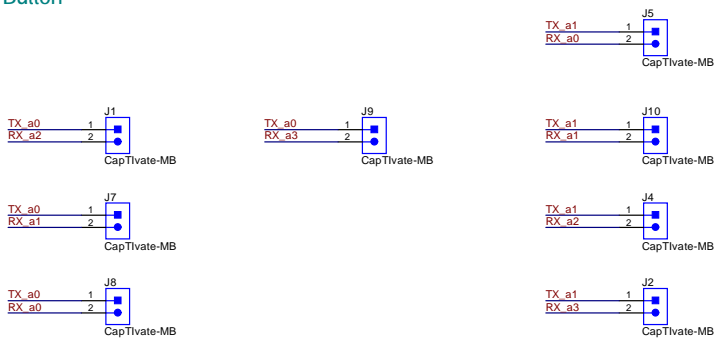
Slider



GesturePad



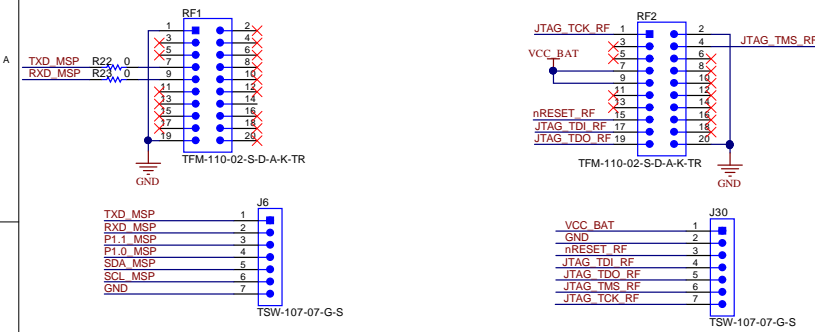
Button



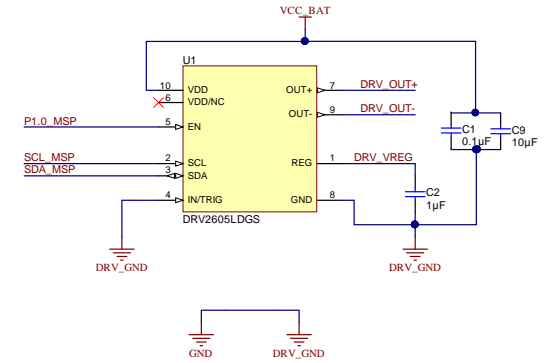
Proximity



Communication Interface Circuit



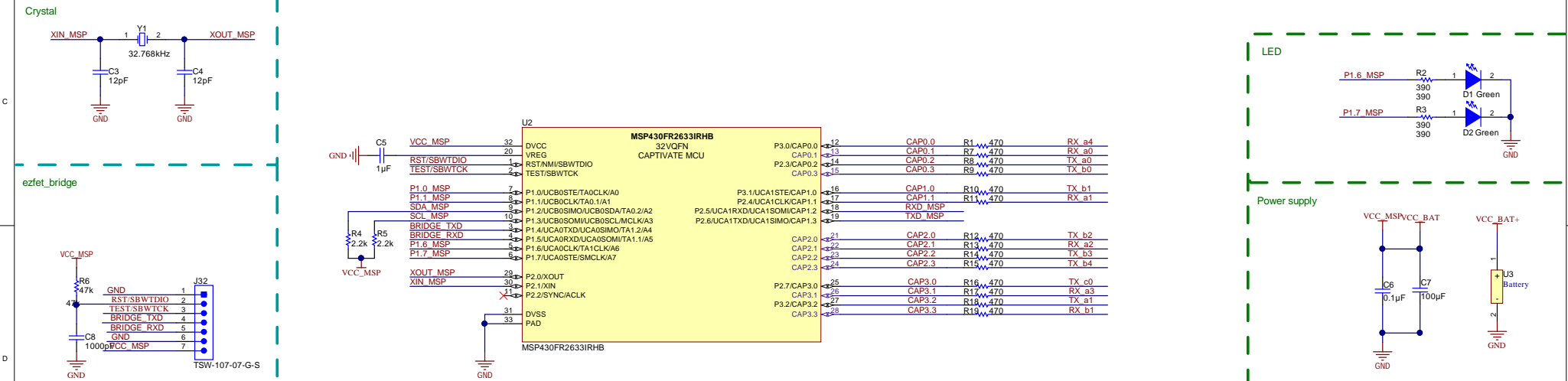
Haptic Drive Circuit



PCB LOGO
ESD Susceptible

PCB LOGO
Texas Instruments

MSP430FR2633 Circuit



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Orderable: NA | Designed for: Public Release | Mod. Date: 9/14/2016
 TID #: TIDM-CAPTIVATE-REMOTECONTROL | Request: Touch Remote Control with CapTivate™ Technology
 Number: TIDM-CAPTIVATE-REMOTECONTROL | Assembly Variant: No Variations | Sheet: 2 of 3
 Rev: Version control disabled | Drawn By: File: TIDM-CAPTIVATE-REMOTECONTROL_Main.SSI | Contact: http://www.ti.com/support
 Engineer: Wei Zhao

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